PRODUCT CHANGE NOTICE

Package Outline Drawing Update for Intersil HPBGA Packaged Products

Refer to:
PCN10113

Date: November 5, 2010

November 5, 2010

To: Our Valued Intersil Customers

Subject: **Package Outline Drawing Update for Intersil HPBGA Packaged Products**

This notice is to inform you that Intersil has updated the POD (Package Outline Drawing) for the listed HPBGA (Heatsink Plastic Ball Grid Array) packaged products. The POD updates are the result of an upgrade in the tooling used in the assembly operations and affect the corner chamfer dimensions of the lid and the thickness of the package base/body. The current and new PODs with the changes identified are included for reference. Both the current and new PODs conform to JEDEC outline MS-034/A variation BAL-2. Revisions to the data sheet specifications incorporating the POD updates are in progress and will be available on the Intersil web site upon release.

Products Affected**:** **ISL59532IKEZ** **ISL59534IKEZ**

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product that conforms to either the current or new POD beginning in ninety days from the date of this notification or until the depletion of existing inventory.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Jon Brewster

Jon Brewster
Intersil Corporation

PCN10113

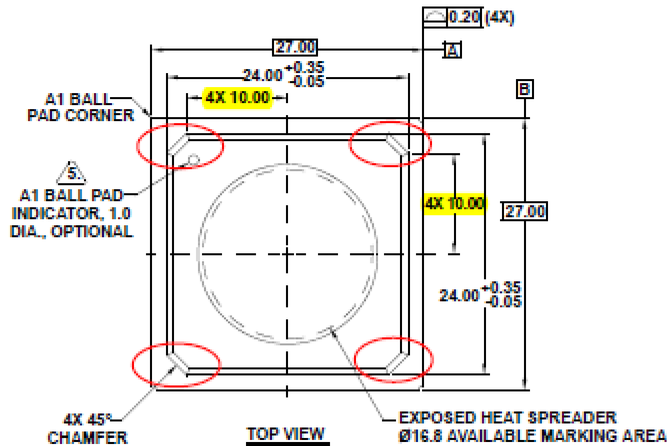
CC: J. Touvell M. Preston J. Bailey K. Tucker

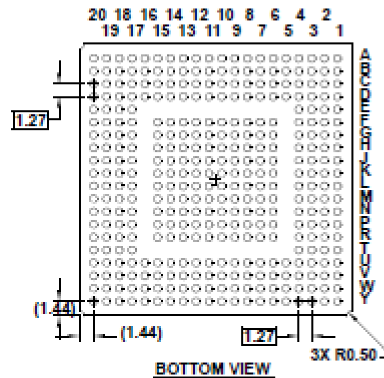
New POD – PCN10113

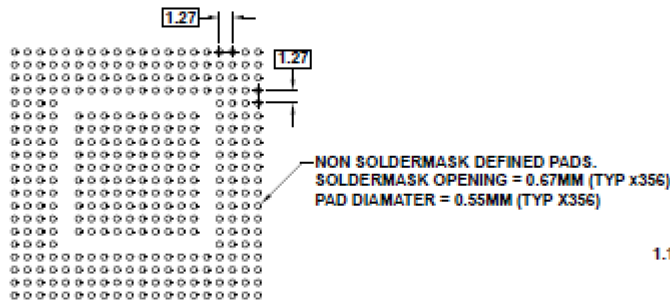
V356.27x27C

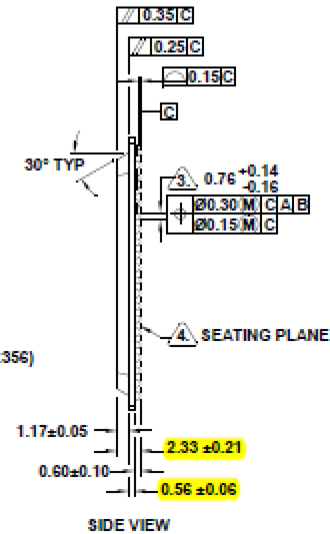
356 BALL HEATSINK PLASTIC BALL GRID ARRAY PACKAGE (HPBGA)

Rev 1, 6/10









NOTES:

1. All dimensions and tolerances conform to ASME Y14.5m-1994.
2. Dimensions are in millimeters.
3. Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
5. A1 ball pad corner I.D. for plate mold: To be marked by ink. Auto mold: Dimple to be formed by mold cap.
6. Reference specifications: This drawing conforms to JEDEC registered outline MS-034/A variation BAL-2.

Current POD – PCN10113